

Uni-polar, Nano Power Hall-Effect Switch IC

1 Product Description

The MT889X family is produced with CMOS technology. The Hall IC internally includes high sensitivity horizontal hall plates, sleep/awake logics for mode control, a low-power on-chip oscillator, low noise analog signal chain with dynamic offset cancellation, hysteresis comparators and an output driver.

The product responds to North pole or South pole magnetic fields. The output will be turned on (Low) when the magnetic flux density (B) is larger than the operating point (BOP), and be turned off (High) when the magnetic flux density (B) is lower than the releasing point (BRP).

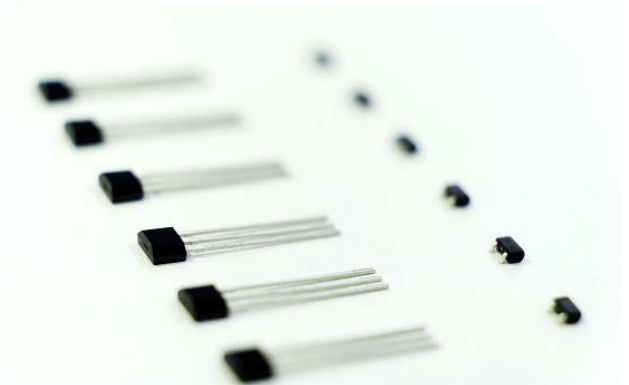
The MT889X family provides a variety of packages to customers: DFN & SOT-23 for surface mount and flat TO-92 for through-hole mount. All packages are RoHS compliant.

2 Features

- CMOS Technology
- Uni-polar Switch
- 1.6 ~ 5V Operating Vcc Range
- -40°C ~ 85°C Operating Temperature
- Package Option:
 - SOT-23
 - Flat TO-92
 - DFN1608
 - DFN1616
- Magnetic Sensitivity Option:
 - BOP=30Gs, BRP=20Gs
- Push Pull Output
- RoHS Compliant: (EU)2015/863

3 Product Overview of MT889X

| Part No. | Description |
|---------------|--|
| MT8891A | Flat TO-92, bulk packaging (1000pcs/bag) |
| MT8891AT | SOT-23, tape & reel (3000pcs/bag) |
| MT8891DT-1608 | DFN1608, tape & reel (10000pcs/bag) |
| MT8891DT-1616 | DFN1616, tape & reel (3000pcs/bag) |



4 Applications

- Home appliances, Industrial
- Position Detection
- Solid-State Switch
- Proximity Switch
- Smart Meter
- Handheld Device
- Consumer Device

5. Pin Configuration and Functions

| | Vcc | Out | GND |
|-------------|-------|------------------|--------|
| SOT-23 | 1 | 2 | 3 |
| Flat TO-92 | 1 | 3 | 2 |
| DFN1608 | 3 | 2 | 1 |
| DFN1616 | 4 | 5 | 2 |
| Description | Power | Output Push Pull | Ground |

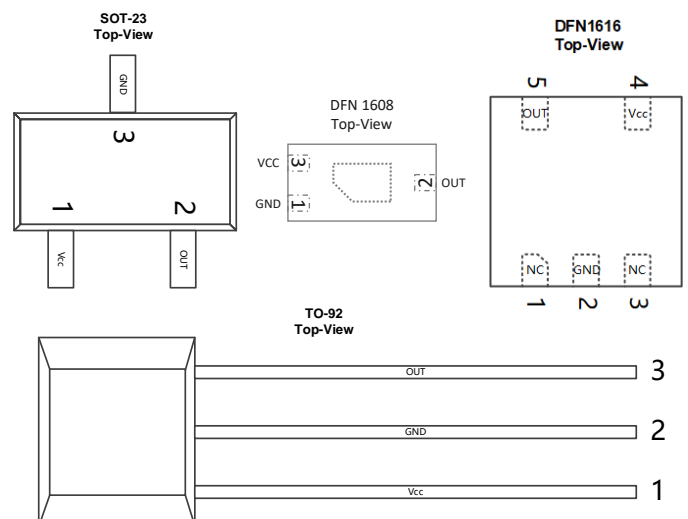


Figure.1 Pin Configuration & Functions

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Reversion History

| | | |
|---|--------------------|--|
| 1 | Originally Version | |
| 2 | 1.1 Version | Update the Supply Voltage SPEC from 3.9V to 5V |

6 Definition of Switching Function

Figure.2 & Figure.3 shows the device functionality and hysteresis

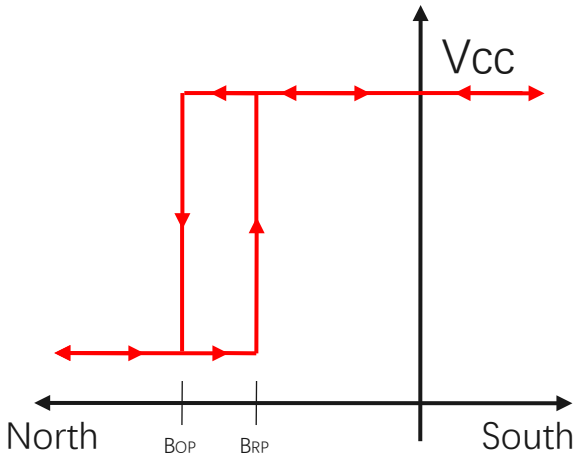


Figure.2 Switching Function Uni-polar (North)
SOT-23

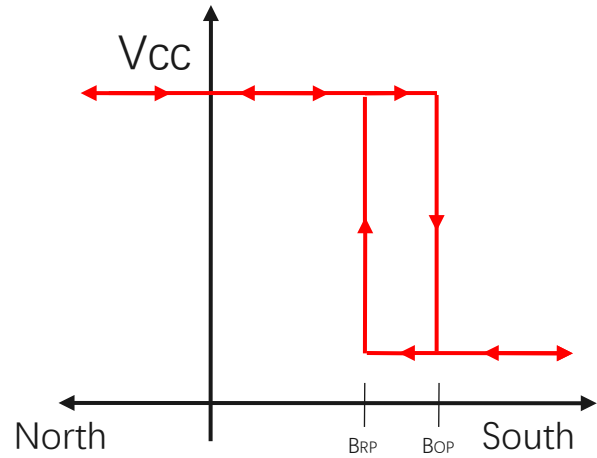


Figure.3 Switching Function Uni-polar (South)
Flat TO-92 / DFN1608 / DFN1616

7 Function Description

B_{OP}: Operating Point, Magnetic flux density applied on the branded side of the package which turns the output driver ON ($V_{OUT}=Low$)

B_{RP}: Releasing Point, Magnetic flux density applied on the branded side of the package which turns the output driver OFF ($V_{OUT}=High$)

B_{HYST}: Hysteresis Window, $|B_{OP} - B_{RP}|$

Devices that have a lower magnetic threshold ($V_{OUT}=High$) detect magnets at a farther distance. Higher thresholds ($V_{OUT}=Low$) generally require a closer distance or larger magnet.

8 Feature Description

The MT889X device is sensitive to the magnetic field component that is perpendicular to the top of the package

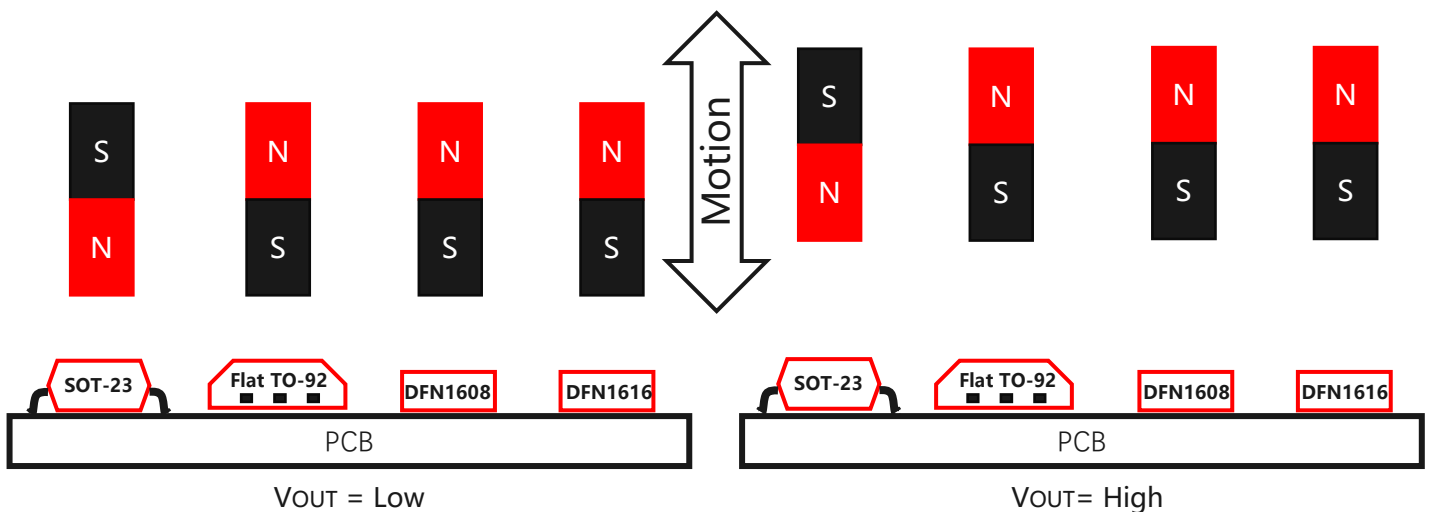


Figure.4 Flux Direction Polarity

9 Functional Block Diagram

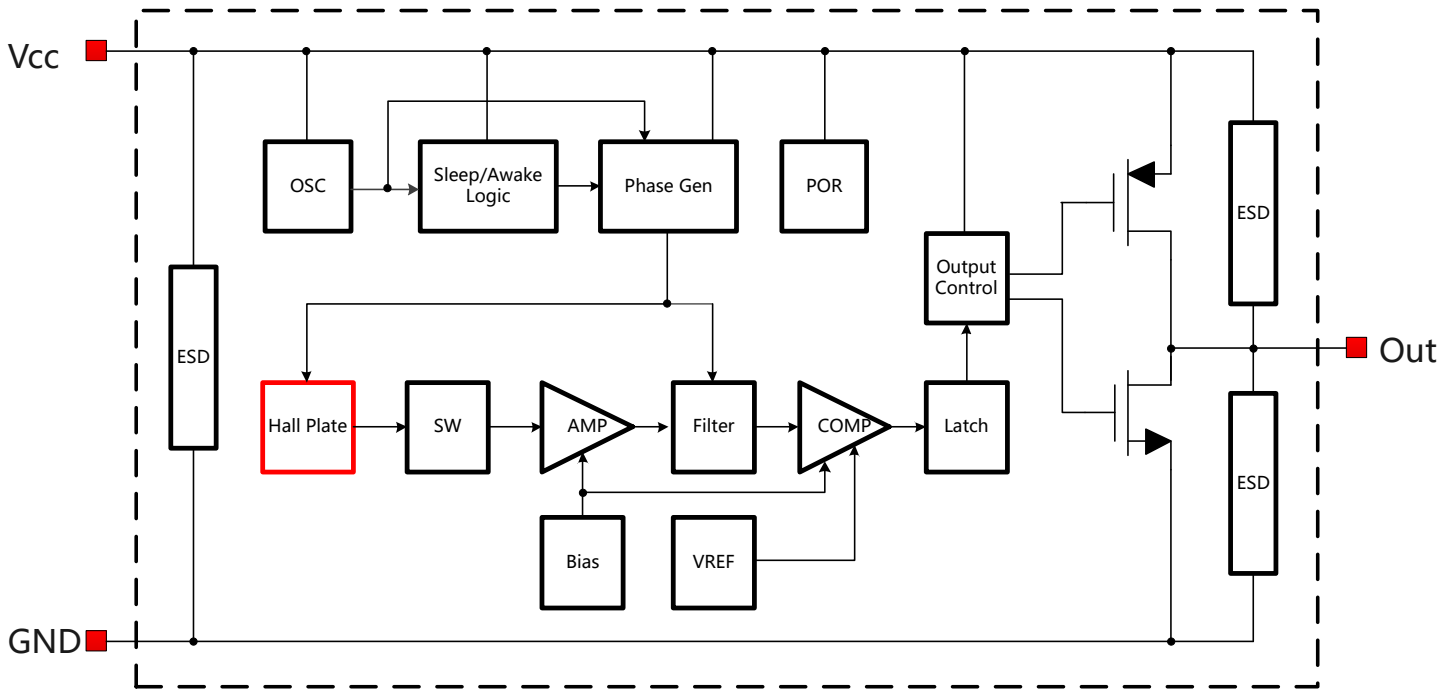


Figure.5 Functional Block Diagram

10 Electrical and Magnetic Characteristics

10.1 Absolute Maximum Ratings

Absolute maximum ratings are limited values to be applied individually, and beyond which the serviceability of the circuit may be impaired. Functional operability is not necessarily implied. Exposure to absolute maximum rating conditions for an extended period of time may affect device reliability.

| Symbol | Parameters | Min | Max | Units |
|--------|-------------------------------|----------|-----|-------|
| VCC | Supply Voltage | - | 7 | V |
| VRCC | Reverse Battery Voltage | -0.5 | - | V |
| VOUT | Output Voltage | - | 7 | V |
| IOUT | Continuous Output Current | - | 3 | mA |
| TA | Operating Ambient Temperature | -40 | 85 | °C |
| TS | Storage Temperature | -50 | 150 | °C |
| TJ | Junction Temperature | - | 165 | °C |
| B | Magnetic Flux Density | No Limit | | Gs |

10.2 Electrical Specifications

At $T_A = -40 \sim 85^\circ\text{C}$, $V_{CC} = 1.6\text{V} \sim 5\text{V}$ (unless otherwise specified)

| Symbol | Parameters | Test Condition | Min | Typ | Max | Unit |
|----------|----------------------------------|--|----------------|------|-----|---------------------------|
| V_{CC} | Supply Voltage | Operating | 1.6 | - | 5 | V |
| I_{CC} | Supply Current | $V_{CC} = 3.3\text{V}$ | - | 1.7 | - | μA |
| | | $V_{CC} = 1.6\text{V}$ | - | 1.0 | - | μA |
| I_{AW} | Awake Current | $V_{CC} = 3.3\text{V}$ | - | 2.5 | - | mA |
| I_{SL} | Sleep Current | $V_{CC} = 3.3\text{V}$ | - | 1.0 | - | μA |
| V_{OL} | Output Low Voltage | $I_{OUT} = 1\text{mA}$, $ B > B_{OP} $ | - | - | 0.4 | V |
| V_{OH} | Output High Voltage | $I_{OUT} = 1\text{mA}$, $ B < B_{RP} $ | $V_{CC} - 0.4$ | - | - | V |
| F_{SW} | Switching Frequency | $V_{CC} = 3.3\text{V}$ | 10 | 20 | 40 | Hz |
| T_{AW} | Awake Time | $V_{CC} = 1.6\text{V}$ to 5V | 6 | 10 | 24 | μs |
| T_{SL} | Sleep Time | $V_{CC} = 1.6\text{V}$ to 5V | 25 | 50 | 105 | ms |
| D.C. | Duty Cycle | $V_{CC} = 1.6\text{V}$ to 5V | - | 0.02 | - | % |
| T_{PO} | Power on Time | $dV_{CC}/dt > 5\text{V}/\mu\text{s}$, $ B > B_{OP} $ | - | - | 120 | μs |
| R_{TH} | Thermal Resistance of SOT-23 | | - | 301 | - | $^\circ\text{C}/\text{W}$ |
| | Thermal Resistance of DFN | | - | 301 | - | $^\circ\text{C}/\text{W}$ |
| | Thermal Resistance of Flat TO-92 | | - | 230 | - | $^\circ\text{C}/\text{W}$ |

10.3 Magnetic Characteristics

At $V_{CC} = 1.6\text{V} \sim 5\text{V}$ (unless otherwise specified)

| Part No. | Symbol | Min | Typ | Max | Unit |
|---------------|---------------------------------------|-----|-----|-----|------|
| MT8891 Series | B_{OP} , $T_A = 25^\circ\text{C}$ | 20 | 30 | 40 | Gs |
| | B_{RP} , $T_A = 25^\circ\text{C}$ | 10 | 20 | 30 | Gs |
| | B_{HYST} , $T_A = 25^\circ\text{C}$ | - | 10 | - | Gs |

10.4 ESD Ratings

| Symbol | Reference | Values | Unit | |
|-----------|----------------------------|--------------|------------|---|
| V_{ESD} | Human-body model (HBM) | AEC-Q100-002 | ± 5000 | V |
| | Charged-device model (CDM) | AEC-Q100-011 | ± 1000 | V |

10.5 Characteristic Performance

At $V_{CC}=3.3V$

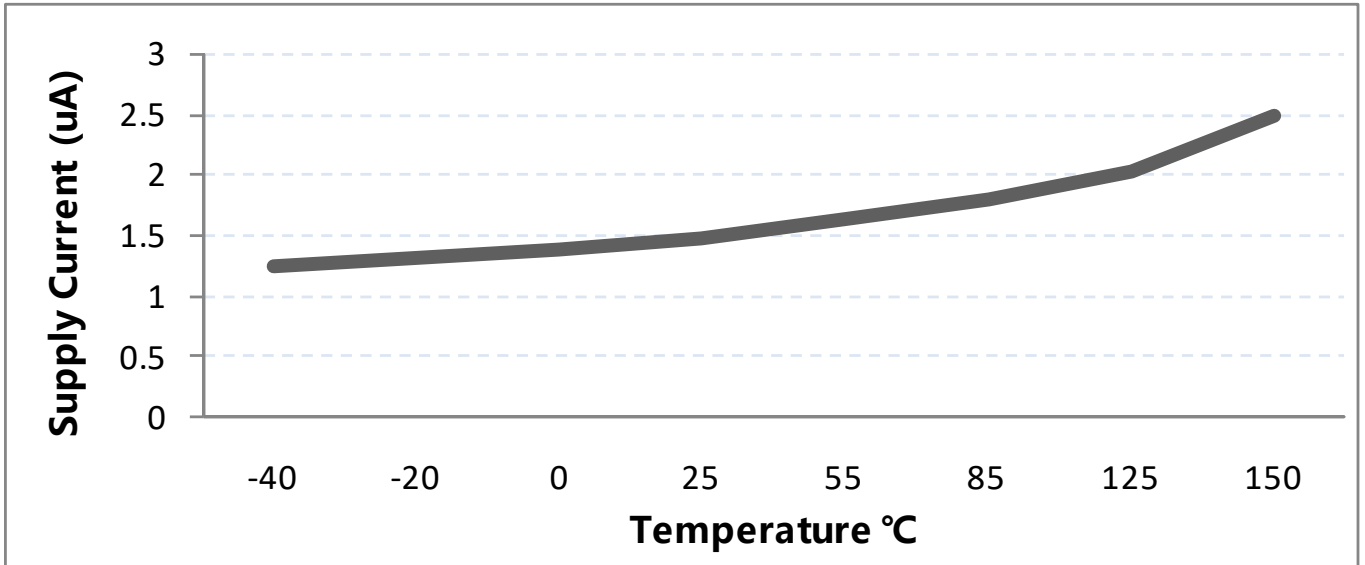


Figure.6 Supply Current vs. Temperature

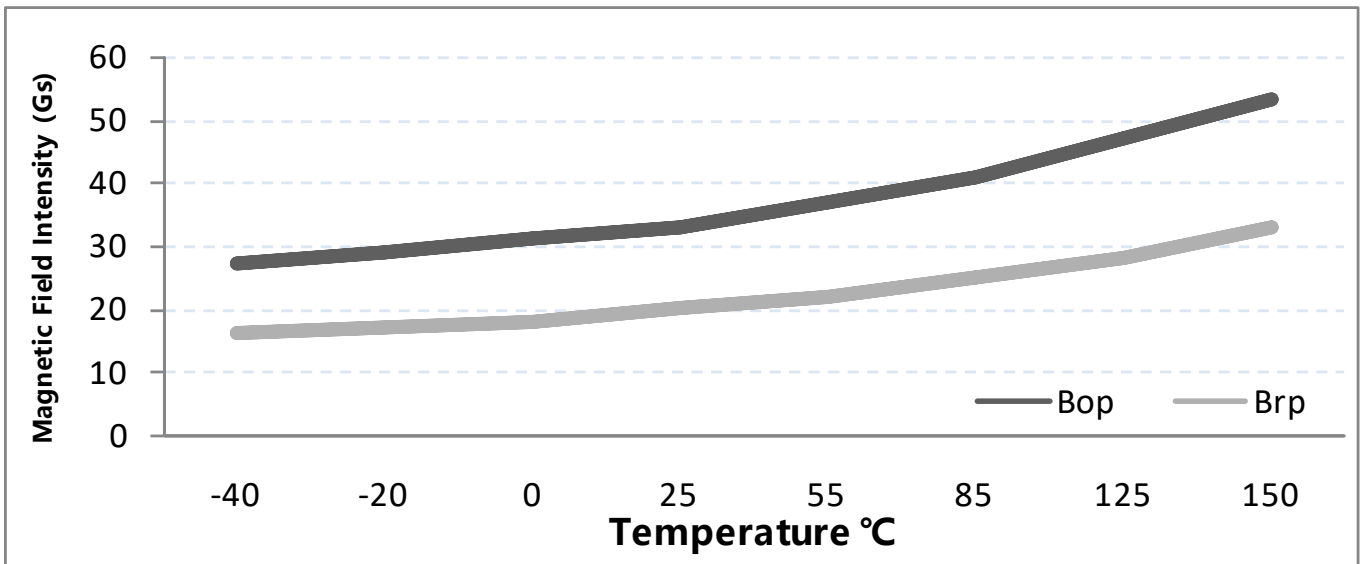


Figure.7 Magnetic Characteristics vs. Temperature (BOP & BRP)

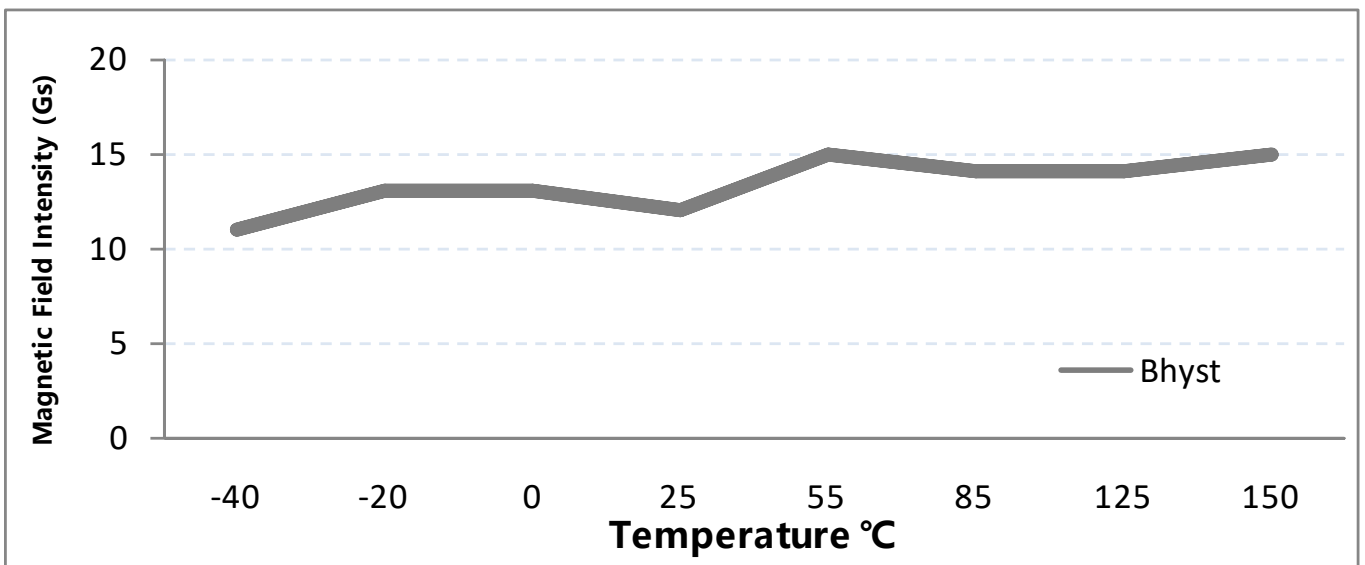


Figure.8 Magnetic Characteristics vs. Temperature (BHYST)

10.6 Typical Output Waveform

MT8891A as example

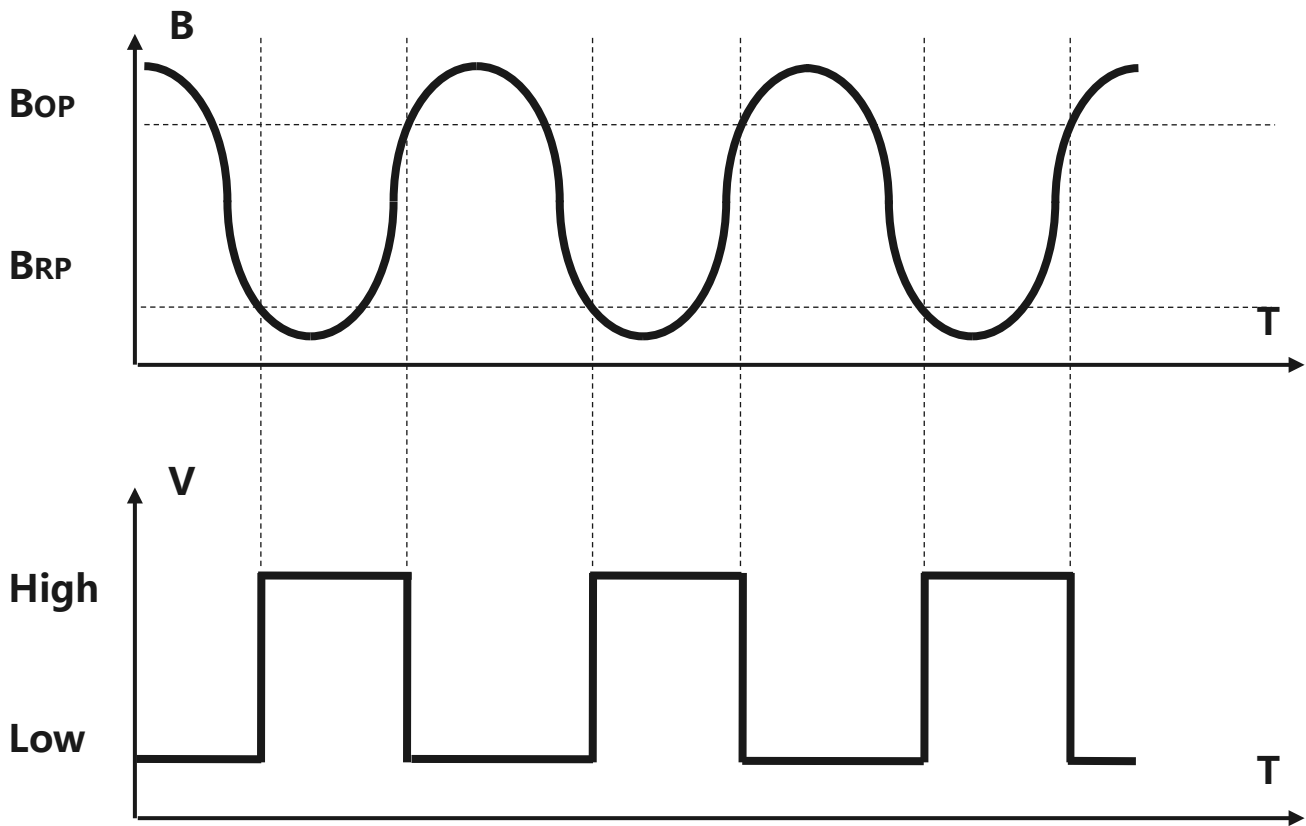


Figure.9 Digital Output vs. Magnetic Flux Density

11 Typical Application Circuit

MT8891AT as example

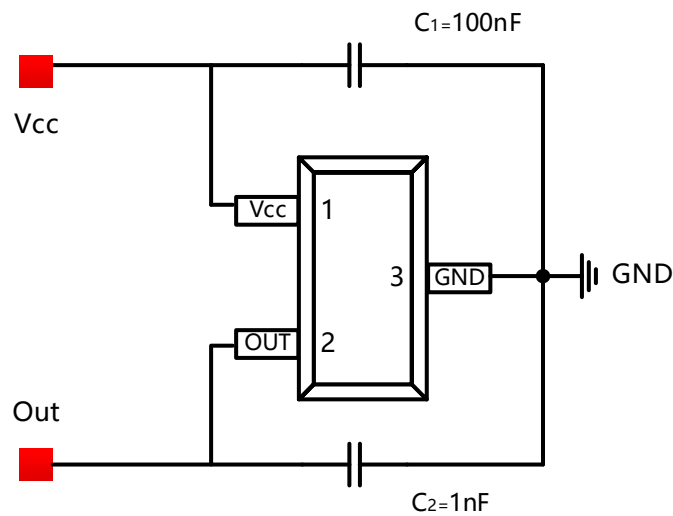


Figure.10 Typical Application Circuit

12 Package Material Information (For Reference Only – Not for Tooling Use)

12.1 SOT-23 Package Information

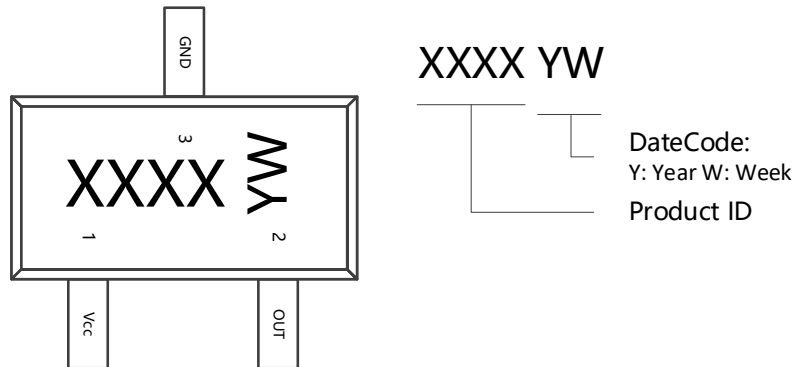


Figure.11 SOT-23 Chip Marking Spec

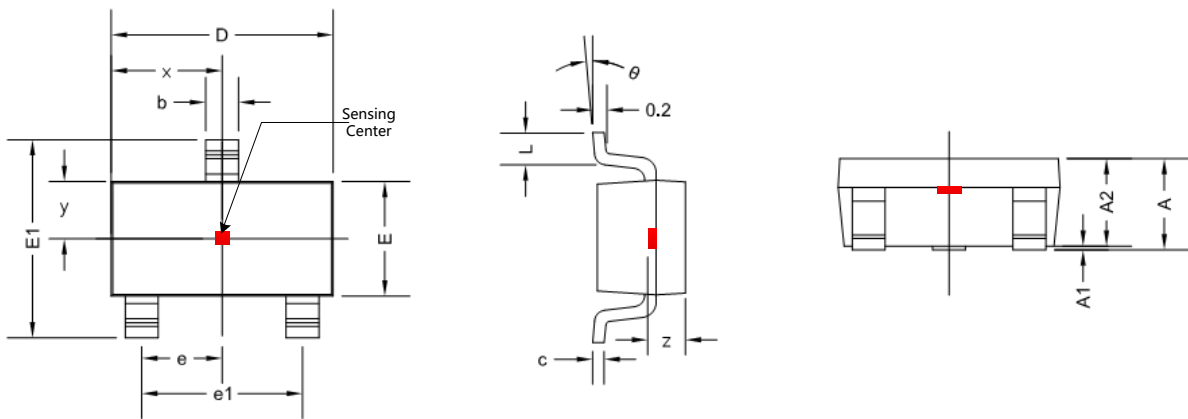


Figure.12 SOT-23 Package Drawing

| Symbol | Dimensions in Millimeters | | Dimensions in Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.050 | 1.300 | 0.041 | 0.051 |
| A1 | 0.000 | 0.150 | 0.000 | 0.006 |
| A2 | 1.000 | 1.200 | 0.039 | 0.047 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.080 | 0.220 | 0.003 | 0.009 |
| D | 2.800 | 3.020 | 0.110 | 0.119 |
| E | 1.500 | 1.700 | 0.059 | 0.067 |
| E1 | 2.600 | 3.000 | 0.102 | 0.118 |
| e | 0.950 TYP | | 0.037 TYP | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.300 | 0.600 | 0.012 | 0.024 |
| θ | 0 ° | 8 ° | 0 ° | 8 ° |
| x | 1.460 TYP | | 0.057 TYP | |
| y | 0.800 TYP | | 0.032 TYP | |
| z | 0.600 TYP | | 0.024 TYP | |

12.2 Flat TO-92 Package Information

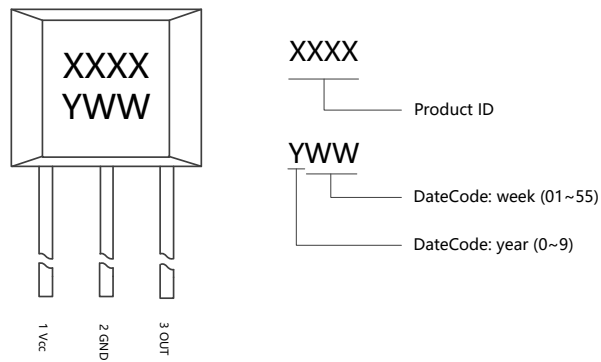


Figure.13 Flat TO-92 Chip Marking Spec

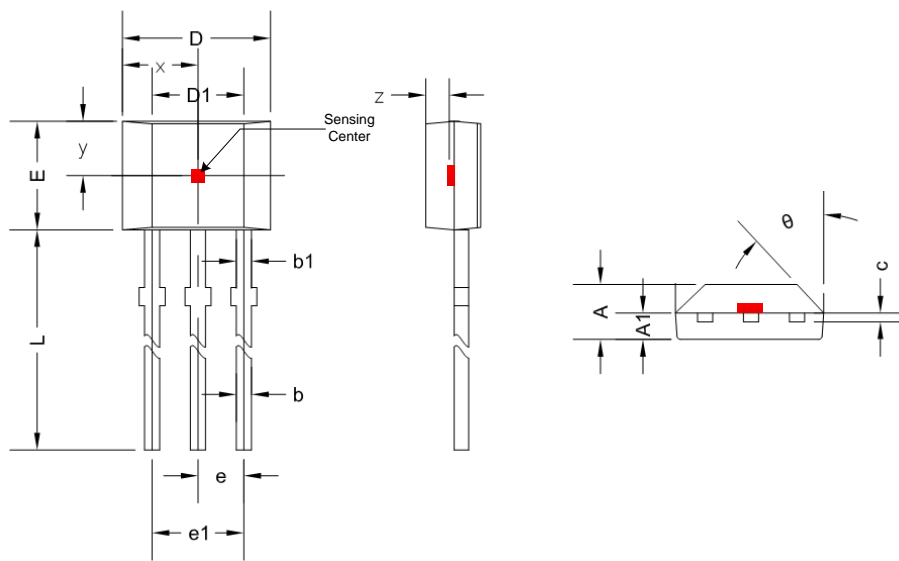
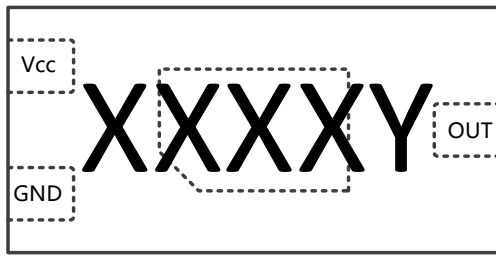


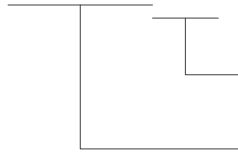
Figure.14 Flat TO-92 Package Drawing

| Symbol | Dimensions in Millimeters | | Dimensions in Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.420 | 1.620 | 0.056 | 0.064 |
| A1 | 0.660 | 0.910 | 0.026 | 0.036 |
| b | 0.330 | 0.560 | 0.013 | 0.022 |
| b1 | 0.400 | 0.510 | 0.016 | 0.020 |
| c | 0.330 | 0.510 | 0.013 | 0.020 |
| D | 3.900 | 4.200 | 0.154 | 0.165 |
| D1 | 2.280 | 2.680 | 0.090 | 0.106 |
| E | 2.900 | 3.280 | 0.114 | 0.128 |
| e | 1.270 TYP | | 0.050 TYP | |
| e1 | 2.440 | 2.640 | 0.096 | 0.104 |
| L | 13.500 | 16.200 | 0.531 | 0.638 |
| θ | 45 ° TYP | | 45 ° TYP | |
| x | 2.025 TYP | | 0.080 TYP | |
| y | 1.545 TYP | | 0.061 TYP | |
| z | 0.500 TYP | | 0.020 TYP | |

12.3 DFN1608 Package Information



XXXX Y



DateCode: week (A~z)

Product ID

Figure.15 DFN1608 Chip Marking Spec

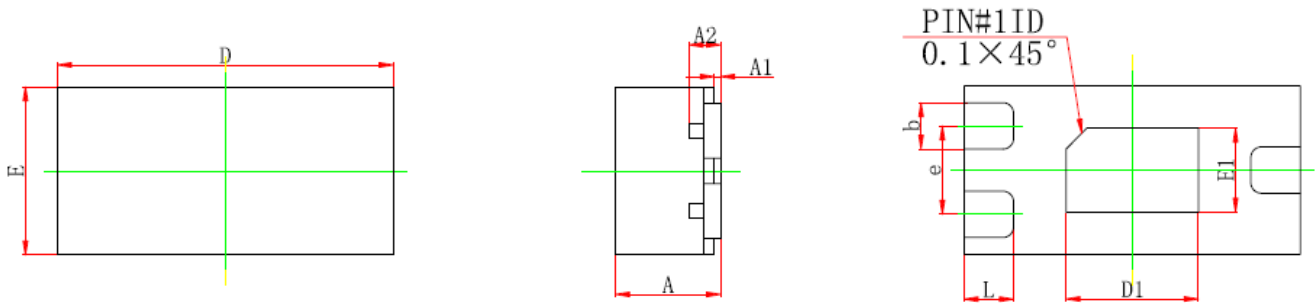


Figure.16 DFN1608 Package Drawing

| Symbol | Dimensions in Millimeters | | Dimensions in Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 0.450 | 0.550 | 0.018 | 0.022 |
| A1 | 0.000 | 0.050 | 0.000 | 0.002 |
| A2 | 0.150 TYP | | 0.006 TYP | |
| D | 1.550 | 1.650 | 0.061 | 0.065 |
| E | 0.750 | 0.850 | 0.030 | 0.033 |
| D1 | 0.580 | 0.680 | 0.023 | 0.027 |
| E1 | 0.350 | 0.450 | 0.014 | 0.018 |
| b | 0.170 | 0.270 | 0.007 | 0.011 |
| e | 0.420 TYP | | 0.017 TYP | |
| L | 0.185 | 0.285 | 0.007 | 0.011 |

12.4 DFN1616 Package Information

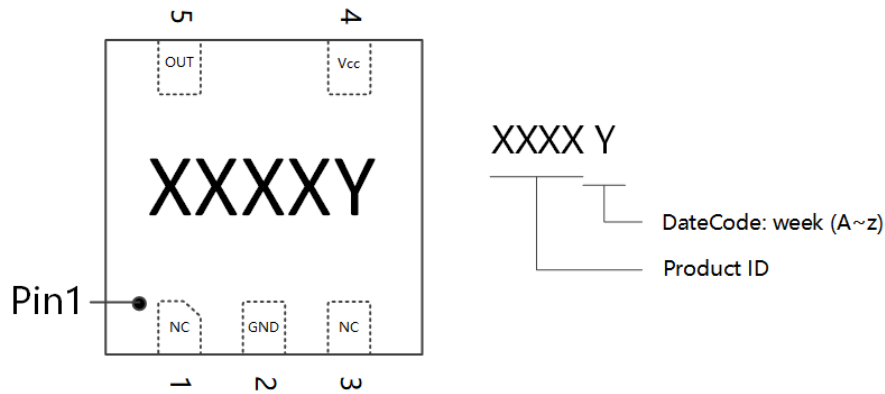


Figure.17 DFN1616 Chip Marking Spec

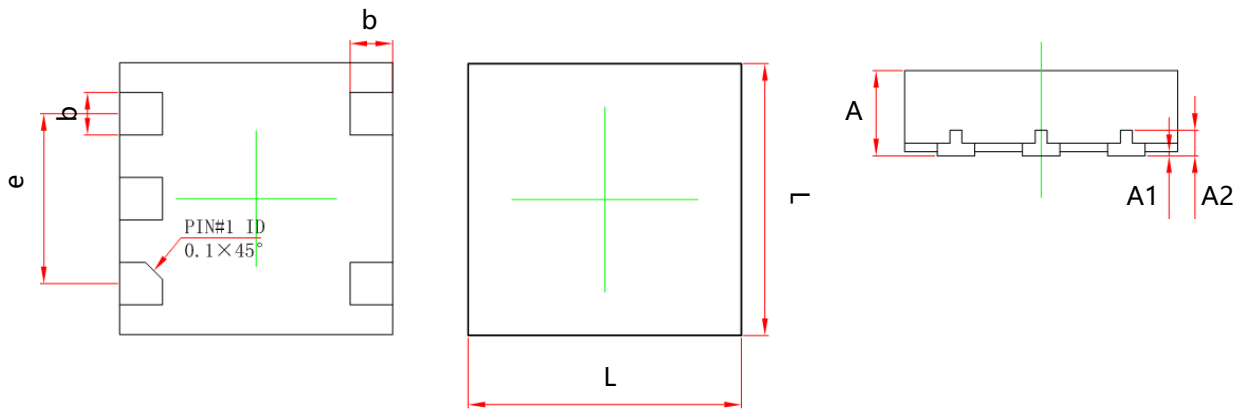


Figure.18 DFN1616 Package Drawing

| Symbol | Dimensions in Millimeters | | Dimensions in Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 0.450 | 0.550 | 0.018 | 0.022 |
| A1 | 0.000 | 0.050 | 0.000 | 0.002 |
| A2 | 0.150 TYP | | 0.006 TYP | |
| L | 1.550 | 1.650 | 0.061 | 0.065 |
| b | 0.200 | 0.300 | 0.008 | 0.012 |
| e | 1.000 TYP | | 0.039 TYP | |

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